

I claim:

1. A heat-radiating structure of chip disposed around a flip chip type chip on a circuit substrate, comprising:
 - a heat-radiating sheet for conducting out heat of said chip; and
 - 5 a bearing rack extended from said heat-radiating sheet and disposed near sides of said heat-radiating sheet facing a surface of said chip, an adhesive being connected between a top face of said chip and a surface of said heat-radiating sheet.
- 10 2. The heat-radiating structure of chip as claimed in claim 1, wherein at least a groove surrounding said chip is disposed at the surface of said heat-radiating sheet facing said chip.
3. The heat-radiating structure of chip as claimed in claim 1, wherein a projective portion is disposed at the surface of said heat-radiating sheet facing said chip.
- 15 4. The heat-radiating structure of chip as claimed in claim 3, wherein said heat-radiating sheet uses a surface of said projective portion to connect a surface of said chip.
5. The heat-radiating structure of chip as claimed in claim 3, wherein at least a groove surrounding said chip is disposed beside said projective portion of
- 20 said heat-radiating sheet facing the surface of said chip.
6. The heat-radiating structure of chip as claimed in claim 1, wherein said chip and said circuit substrate are connected together with adhesive.
7. The heat-radiating structure of chip as claimed in claim 1, wherein said bearing rack is of a square ring shape.
- 25 8. The heat-radiating structure of chip as claimed in claim 1, wherein said

bearing rack is of a circular ring shape.

9. A heat-radiating structure of chip disposed around a flip chip type chip on a circuit substrate, comprising:

a heat-radiating sheet for conducting out heat of said chip; and

5 a bearing rack extended from said heat-radiating sheet and disposed near sides of said heat-radiating sheet facing a surface of said chip, said bearing rack being divided into at least two parts, an adhesive being connected between a top face of said chip and a surface of said heat-radiating sheet.

10 10. The heat-radiating structure of chip as claimed in claim 9, wherein at least a groove surrounding said chip is disposed at the surface of said heat-radiating sheet facing said chip.

11. The heat-radiating structure of chip as claimed in claim 9, wherein a projective portion is disposed at the surface of said heat-radiating sheet facing said chip.

15 12. The heat-radiating structure of chip as claimed in claim 11, wherein said heat-radiating sheet uses a surface of said projective portion to connect a surface of said chip.

20 13. The heat-radiating structure of chip as claimed in claim 11, wherein at least a groove surrounding said chip is disposed beside said projective portion of said heat-radiating sheet facing the surface of said chip.

14. The heat-radiating structure of chip as claimed in claim 9, wherein said chip and said circuit substrate are connected together with adhesive.

15. The heat-radiating structure of chip as claimed in claim 9, wherein said bearing rack is of a square ring shape.

25 16. The heat-radiating structure of chip as claimed in claim 9, wherein said

bearing rack is of a circular ring shape.

17. A heat-radiating structure of chip disposed around a flip chip type chip on a circuit substrate, comprising:

a heat-radiating sheet for conducting out heat of said chip; and

5 a bearing rack extended from said heat-radiating sheet and disposed near sides of said heat-radiating sheet facing a surface of said chip, each side of said bearing rack being divided into at least two parts, each side of said bearing rack being not connected together, an adhesive being connected between a top face of said chip and a surface of said heat-radiating sheet.

10 18. The heat-radiating structure of chip as claimed in claim 17, wherein at least a groove surrounding said chip is disposed at the surface of said heat-radiating sheet facing said chip.

15 19. The heat-radiating structure of chip as claimed in claim 17, wherein a projective portion is disposed at the surface of said heat-radiating sheet facing said chip.

20. The heat-radiating structure of chip as claimed in claim 19, wherein said heat-radiating sheet uses a surface of said projective portion to connect a surface of said chip.